

Filename: PMP4629 REV_B_bom.xls

Date: 08/10/2009

PMP4629 REV_B BOM

| COUNT | RefDes | Value | Description | Size | Part Number | Mfr |
|-------|--------|--------------|--|--------------------|--------------------|-------------------|
| 1 | C2 | 220uF | Capacitor, Electrolytic, High Current, KZE Series, 20% | 0.492 inch | EKZE630ESS221MJ25S | Nippon Chemicon |
| 2 | C3 | 3.3uF | Capacitor, Ceramic, 50-V, X5R, 20% | 1210 | C3225X5R1H335M | TDK |
| | C4 | 3.3uF | Capacitor, Ceramic, 50-V, X5R, 20% | 1210 | C3225X5R1H335M | TDK |
| 1 | C5 | 100pF | Capacitor, Ceramic, 50V, C0G, 5% | 0603 | C1608C0G1H101J | TDK |
| 1 | C6 | 3.9nF | Capacitor, Ceramic, 50V, X7R, 10% | 0603 | Std | Std |
| 1 | C7 | 39pF | Capacitor, Ceramic, 50V, X7R, 10% | 0603 | Std | Std |
| 1 | C8 | 0.1uF | Capacitor, Ceramic, 50V, X7R, 10% | 0603 | C1608X7R1H104K | TDK |
| 3 | C9 | 100uF | Capacitor, Ceramic, 6.3V, X5R, 20% | 1210 | C3225X5R0J107M | TDK |
| | C11 | 100uF | Capacitor, Ceramic, 6.3V, X5R, 20% | 1210 | C3225X5R0J107M | TDK |
| | C12 | 100uF | Capacitor, Ceramic, 6.3V, X5R, 20% | 1210 | C3225X5R0J107M | TDK |
| 1 | C13 | 470pF | Capacitor, Ceramic, 50V, X7R, 10% | 0603 | Std | Std |
| 1 | C14 | 0.47uF | Capacitor, Ceramic, 16V, X7R, 10% | 0603 | C1608X7R1C474M | TDK |
| 1 | C15 | 560pF | Capacitor, Ceramic, 50V, X7R, 10% | 0603 | Std | Std |
| 1 | D1 | MBRD660CT | Diode, Schottky, 6-A, 60-V | DPAK | MBRD660CT | ON Semiconductor |
| 2 | J1 | ED1514 | Terminal Block, 2-pin, 6-A, 3.5mm | 0.27 x 0.25 | ED1514 | OST |
| | J2 | ED1514 | Terminal Block, 2-pin, 6-A, 3.5mm | 0.27 x 0.25 | ED1514 | OST |
| 1 | L2 | 15uH | Inductor, SMT, 7.3-A, 30-milliohm | 0.484 x 0.484 inch | MSS1278-153ML | Coilcraft |
| 1 | Q1 | SQD19P06-60L | MOSFET, P-ch, 60-V, 19-A, 55 milli-Ohm | DPAK | SQD19P06-60L | Vishay |
| 2 | R1 | 100k | Resistor, Chip, 1/16W, 1% | 0603 | Std | Std |
| 1 | R2 | 0.01 | Resistor, 1/2W, yy% | 1210 | Std | Std |
| 1 | R3 | 1k | Resistor, Chip, 1/16W, 1% | 0603 | Std | Std |
| 1 | R4 | 0 | Resistor, Chip, 1/16W, 1% | 0603 | Std | Std |
| 1 | R5 | 41.2k | Resistor, Chip, 1/16W, 1% | 0603 | Std | Std |
| 1 | R6 | 2.87k | Resistor, Chip, 1/16W, 1% | 0603 | Std | Std |
| | R7 | 100k | Resistor, Chip, 1/16W, 1% | 0603 | Std | Std |
| 1 | R8 | 49.9 | Resistor, Chip, 1/16W, 1% | 0603 | Std | Std |
| 1 | R9 | 19.6k | Resistor, Chip, 1/16W, 1% | 0603 | Std | Std |
| 5 | TP1 | | Test Point, Red, 1mm | 0.038 | 240-345 | Farnell |
| 3 | TP2 | | Test Point, Black, 1mm | 0.038 | 240-333 | Farnell |
| | TP4 | | Test Point, Red, 1mm | 0.038 | 240-345 | Farnell |
| | TP5 | | Test Point, Red, 1mm | 0.038 | 240-345 | Farnell |
| | TP6 | | Test Point, Black, 1mm | 0.038 | 240-333 | Farnell |
| | TP7 | | Test Point, Black, 1mm | 0.038 | 240-333 | Farnell |
| | TP8 | | Test Point, Red, 1mm | 0.038 | 240-345 | Farnell |
| | TP9 | | Test Point, Red, 1mm | 0.038 | 240-345 | Farnell |
| 1 | U1 | TPS40200D | IC, Low Cost Sync Buck Controller | SO-8 | TPS40200D | Texas Instruments |

- Notes:
1. These assemblies are ESD sensitive, ESD precautions shall be observed.
 2. These assemblies must be clean and free from flux and all contaminants.
Use of no clean flux is not acceptable.
 3. These assemblies must comply with workmanship standards IPC-A-610 Class 2.
 4. Ref designators marked with an asterisk (***) cannot be substituted.
All other components can be substituted with equivalent MFG's components.

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